

M74HC646 M74HC648

HC646 OCTAL BUS TRANSCEIVER/REGISTER (3-STATE) HC648 OCTAL BUS TRANSCEIVER/REGISTER (3-STATE, INV.)

- HIGH SPEED
- f_{MAX} = 73 MHz (TYP.) AT V_{CC} = 5 V ■ LOW POWER DISSIPATION
- $I_{CC} = 4 \ \mu A \ (MAX.) \ AT \ T_A = 25 \ ^{\circ}C$
- HIGH NOISE IMMUNITY VNIH = VNIL = 28 % VCC (MIN.)
- OUTPUT DRIVE CAPABILITY 15 LSTTL LOADS
- SYMMETRICAL OUTPUT IMPEDANCE | I_{OH} |= I_{OL} = 6 mA (MIN.)
- BALANCED PROPAGATION DELAYS tPLH = tPHL
- WIDE OPERATING VOLTAGE RANGE V_{CC} (OPR) = 2 V TO 6 V
- PIN AND FUNCTION COMPATIBLE WITH 54/74LS646/648

DESCRIPTION

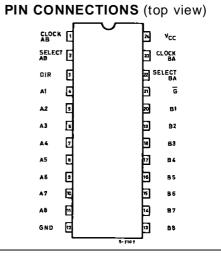
The M74HC646/648 are high speed CMOS OCTAL BUS TRANSCEIVERS AND REGISTERS, (3-STATE) fabricated in silicon gate C²MOS technology. They have the same high speed performance of LSTTL combined with true CMOS low power consumption.

These devices consist of bus transceiver circuits with 3-state output, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus will be clocked into the registers on the low-to-high transition of the appropriate clock pin (Clock AB - or Clock BA). Enable (\overline{G}) and direction (DIR) pins are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both.

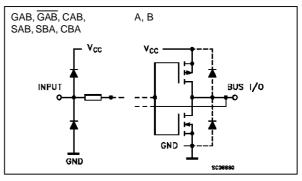
The select controls (Select AB select BA) can multiplex stored and real-time (transparent mode) data. The direction control determines which bus will receive data when enable \overline{G} is active (low).

In the isolation mode (enable \overline{G} high), "A" data may be stored in one register and/or "B" data may be stored in the other register. When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time. All inputs are equipped with protection circuits

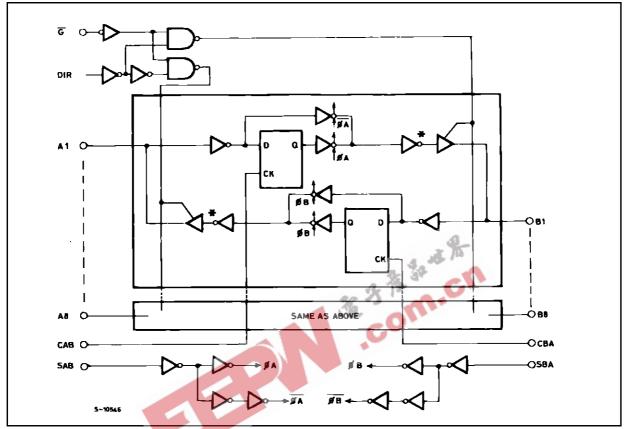




INPUT AND OUTPUT EQUIVALENT CIRCUIT

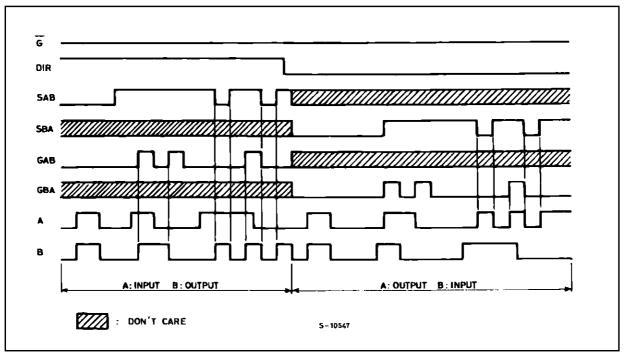


LOGIC DIAGRAM (HC648)



Note : In case of M54/74HC646 output inverter marked * at A bus and B bus are eliminated.

TIMING CHART





TRUTH TABLE

HC646 (The truth table for HC648 is the same as this, but with the outputs inverted)

G	DIR	CAB	СВА	SAB	SBA	Α	В	FUNCTION
						INPUTS	INPUTS	Both the A bus and the B bus are inputs
		Х	Х	Х	Х	Z	Z	The output functions of the A and B bus are disabled
н	X			Х	X	INPUTS	INPUTS	Both the A and B bus are used for inputs to the internal flip-flops. Data at the bus will be stored on low to high transition of the clock inputs
						INPUTS	OUTPUTS	The A bus are inputs and the B bus are outputs
		X	X*	L	X	L	L	The data at the A bus are displayed at the B bus
						Н	Н	
			X*	L	X	L	L	The data at the A bus are displayed at the B bus.
L	н					Н	Н	The data of the A bus are stored to the internal flip-flop on low to high transition of th clock pulse.
		Х	X*	Н	X	Х	Qn	The data stored to the internal flip-flop are dispayed at the B bus
			X*	Н	X	L	L	The data at the A bus are stored to the internal flip-
						Н	н	flop on low to high transition of the clock pulse. The states of the internal flip-flops output directly to the B bus
						OUTPUTS	INPUTS	The B bus are inputs and the A bus are outputs
		X*	х	х	L	L	L H	The data at the B bus are displayed at the A bus
		X*	Г	Х	L		X L T	The data at the B bus are displayed at the A bus.
L	L					Н	Н	The data of the B bus are stored to the internal flip- flop on low to high transition of the clock pulse
		X*	Х	Х	H	Qn	Х	The data stored to the internal flip-flops are displayed at the A bus
		x*		Х	Н	L	L	the data at the B bus are stored to the internal flip-
						Н	Н	flop on low to high transition of the clock pulse. The states of the internal flip-flops output directly to the A bus

X Z : DON'T CARE

: HIGH IMPEDANCE

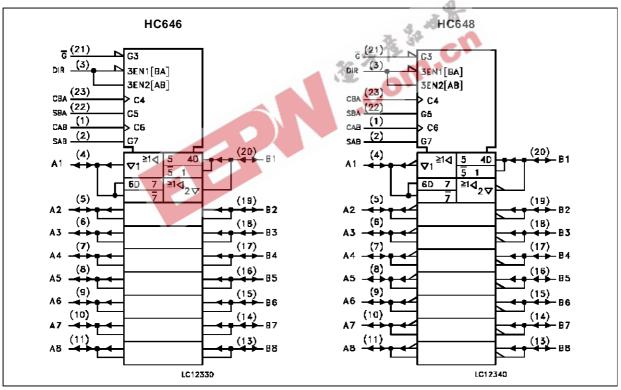
Qn : THE DATA STORED TO THE INTERNAL FLIP-FLOPS BY MOST RECENT LOW TO HIGH TRANSITION OF THE CLOCK INPUTS * : THE DATA AT THE A AND B BUS WILL BE STORED TO THE INTERNAL FLIP-FLOPS ON EVERY LOW TO HIGH TRANSITION OF THE CLOCK INPUTS



PIN DESCRIPTION

PIN No	SYMBOL	NAME AND FUNCTION
1	CLOCK AB	A to B Clock Input (LOW to HIGH, Edge-Trigged)
2	SELECT AB	Select A to B Source Input
3	GAB	Direction Control Input
4, 5, 6, 7, 8, 9, 10, 11	A1 to A8	A data Inputs/Outputs
20, 19, 18, 17, 16, 15, 14, 13	B1 to B8	B Data Inputs/Outputs
21	G	Output Enable Input (Active LOW)
22	SELECT BA	Select B to A Source Input
23	CLOCK BA	B to A Clock Input (LOW to HIGH, Edge-Triggered)
12	GND	Ground (0V)
24	Vcc	Positive Supply Voltage

IEC LOGIC SYMBOLS





ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
Vcc	Supply Voltage	-0.5 to +7	V
VI	DC Input Voltage	-0.5 to V _{CC} + 0.5	V
Vo	DC Output Voltage	-0.5 to V _{CC} + 0.5	V
l _{IK}	DC Input Diode Current	± 20	mA
I _{ОК}	DC Output Diode Current	± 20	mA
lo	DC Output Source Sink Current Per Output Pin	± 35	mA
Icc or I _{GND}	DC V _{CC} or Ground Current	± 70	mA
PD	Power Dissipation	500 (*)	mW
T _{stg}	Storage Temperature	-65 to +150	°C
TL	Lead Temperature (10 sec)	300	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these condition is not implied. (*) 500 mW: \cong 65 °C derate to 300 mW by 10mW/°C: 65 °C to 85 °C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	an Ix	Value	Unit
V _{CC}	Supply Voltage		2 to 6	V
VI	Input Voltage	C	0 to Vcc	V
Vo	Output Voltage		0 to V _{CC}	V
T _{op}	Operating Temperature		-40 to +85	°C
t _r , t _f	Input Rise and Fall Time	$V_{CC} = 2 V$	0 to 1000	ns
		$V_{CC} = 4.5 V$	0 to 500	
		$V_{CC} = 6 V$	0 to 400	



DC SPECIFICATIONS

		Т	est Co	nditions	Value					
Symbol	Parameter				T,	_A = 25 °	Ċ	-40 to	85 °C	Unit
		(V)			Min.	Тур.	Max.	Min.	Max.	
VIH	High Level Input Voltage	2.0			1.5			1.5		
		4.5			3.15			3.15		V
		6.0			4.2			4.2		
VIL	Low Level Input	2.0					0.5		0.5	
	Voltage	4.5					1.35		1.35	V
		6.0					1.8		1.8	
V _{OH}	High Level Output Voltage	2.0	VI =		1.9	2.0		1.9		
		4.5	VI – Vih	I _O =-20 μA	4.4	4.5		4.4		
		6.0	or		5.9	6.0		5.9		V
		4.5	Vı∟	lo=-6.0 mA	4.18	4.31		4.13		
		6.0		l ₀ =-7.8 mA	5.68	5.8	5	5.63		
V _{OL}	Low Level Output Voltage	2.0	Vi =		4	0.0	0.1		0.1	
		4.5	VI – VIH	lo= 20 μA	X	0.0	0.1		0.1	
		6.0	or	- 3R 1.		0.0	0.1		0.1	V
		4.5	VIL	lo= 6.0 mA	.0	0.17	0.26		0.37	
		6.0		lo= 7.8 mA		0.18	0.26		0.37	
l _l	Input Leakage Current	6.0	$V_1 = V_1$	V _{CC} or GND			±0.1		±1	μA
I _{OZ}	3 State Output Off State Current	6.0		V _{IH} or V _{IL} V _{CC} or GND			±0.5		±5.0	μΑ
Icc	Quiescent Supply Current	6.0	$V_i = V_i$	V _{CC} or GND			4		40	μA

AC ELECTRICAL CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

		T	est Co	nditions						
Symbol	Parameter	Vcc	C∟		Т	_A = 25 ^c	°C	-40 to	85 °C	Unit
		(V)	(pF)		Min.	Тур.	Max.	Min.	Max.	
t _{TLH}	Output Transition Time	2.0				25	60		75	
t _{THL}		4.5	50			7	12		15	ns
		6.0				6	10		13	
t _{PLH}	Propagation Delay Time	2.0				74	150		190	
tPHL	(BUS - BUS)	4.5	50			21	30		38	ns
		6.0				18	26		32	
		2.0				91	190		240	
		4.5	150			26	38		48	ns
		6.0				22	32		41	
t _{PLH}	Propagation Delay Time	2.0				98	210		265	
t _{PHL}	(CLOCK - BUS)	4.5	50			28	42		53	ns
		6.0				24	36		45	
		2.0				116	250		315	
		4.5	150			33	50		63	ns
		6.0				28	43		54	

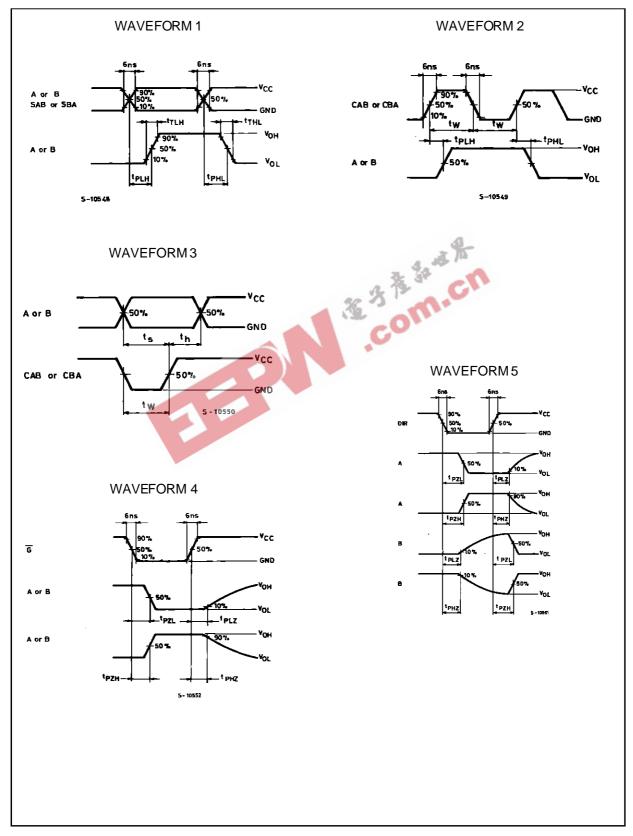


		Т	est Co	nditions	Value					
Symbol	Parameter	Vcc	C∟		Т	_A = 25 ^c	°C	-40 to	85 °C	Unit
		(V)	(pF)		Min.	Тур.	Max.	Min.	Max.	
t _{PLH}	Propagation Delay Time	2.0				81	170		215	
t _{PHL}	(SELECT - BUS)	4.5	50			23	34		43	ns
		6.0				20	29		37	
		2.0				98	210		265	
		4.5	150			28	42		53	ns
		6.0				24	36		45	
t _{PZL}	3-State Output Enable Time	2.0				84	175		220	
t _{PZH}	(G, DIR)	4.5	50	$R_L = 1 \ K\Omega$		24	35		44	ns
		6.0				20	30		37	
		2.0				102	215		270	
		4.5	150	$R_L = 1 \ K\Omega$		29	43		54	ns
		6.0			4	25	37		46	
t _{PLZ}	Output Disable Time	2.0			Se ?	60	175		220	
t _{PHZ}	(G, DIR)	4.5	50	$R_L = 1 \ K\Omega$		23	35		44	ns
		6.0				20	30		37	
f _{MAX}	Maximum Clock Frequency	2.0			6	19		4.8		
		4.5	50		30	67		24		MHz
		6.0			35	79		28		
t _{W(H)}	Minimum Clock Pulse Width	2.0				30	75		95	
t _{W(L)}		4.5 50				7	15		19	ns
		6.0				6	13		16	
ts	Minimum Set-up Time	2.0				16	50		65	
		4.5	50			4	10		13	ns
		6.0				3	9		11	
t _h	Minimum Hold Time	2.0					5		5	
		4.5	50				5		5	ns
		6.0					5		5	
CIN	Input Capacitance					5	10		10	рF
CI/O	Bus Terminal Capacitance					10				pF
C _{PD} (*)	Power Dissipation Capacitance			r HC646 r HC648		39 38				pF

AC ELECTRICAL CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

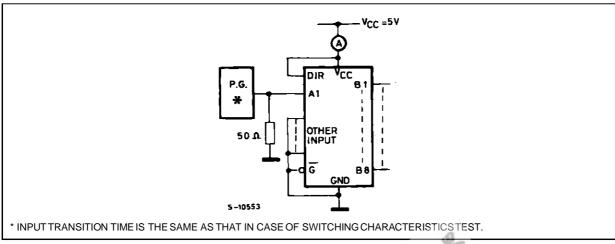
(*) C_{PD} is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operting current can be obtained by the following equation. $I_{CC}(opr) = C_{PD} \bullet V_{CC} \bullet f_{IN} + I_{CC}/8$ (per bit)





SWITCHING CHARACTERISTICS TEST CIRCUIT AND WAVEFORM





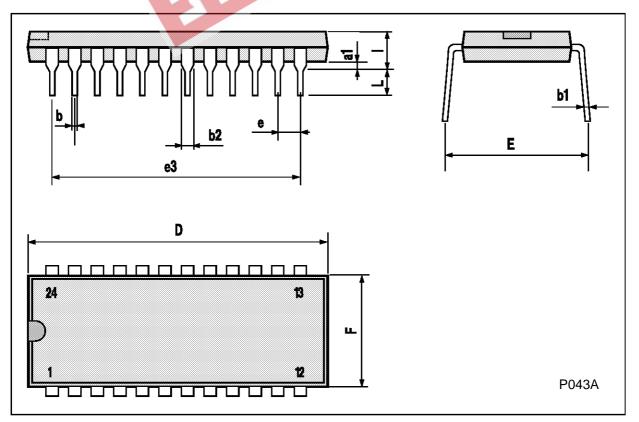
TEST WAVEFORM Icc (Opr.)





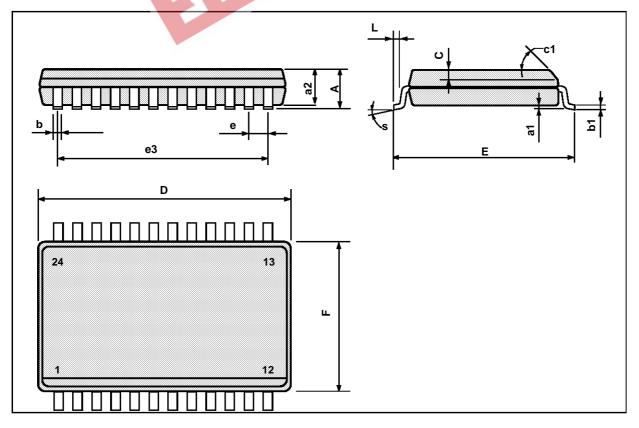
DIM.		mm		inch				
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.		
a1		0.63			0.025			
b		0.45			0.018			
b1	0.23		0.31	0.009		0.012		
b2		1.27			0.050			
D			32.2		-	1.268		
E	15.2		16.68	0.598	A.	0.657		
е		2.54		4 1 St	0.100			
e3		27.94	3	i om	1.100			
F			14.1	.00		0.555		
I		4.445			0.175			
L		3.3			0.130			

Plastic DIP24 (0.25) MECHANICAL DATA



DIM.		mm		inch						
Dim.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.				
А			2.65			0.104				
a1	0.10		0.20	0.004		0.007				
a2			2.45			0.096				
b	0.35		0.49	0.013		0.019				
b1	0.23		0.32	0.009		0.012				
С		0.50			0.020					
c1			45°	(typ.)	2					
D	15.20		15.60	0.598	, ja	0.614				
E	10.00		10.65	0.393	C	0.420				
е		1.27			0.05					
e3		13.97		C	0.55					
F	7.40		7.60	0.291		0.299				
L	0.50		1.27	0.19		0.050				
S	8° (max.)									

SO24 MECHANICAL DATA







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